

**INFORMATION DISCLOSURE CITATION**  
(Use several sheets if necessary)

Docket Number (Optional)

END9200000940S1

Application Number

Applicant(s)

David J. Alcoe

Filing Date

Group Art Unit

**U.S. PATENT DOCUMENTS**

*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
TSP		5,219,794	06/1993	Sato et al.	—	—	
		5,311,402	05/1994	Kobayashi et al.	—	—	
		5,477,933	12/1995	Nguyen	—	—	
		5,894,410	04/1999	Barrow	—	—	
		5,759,737	06/1998	Feilchenfeld et al.	—	—	
TSP		5,634,268	06/1997	Dala et al.	—	—	

JP945 U.S. PTO  
09/71473  
11/16/98

**FOREIGN PATENT DOCUMENTS**

REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO

**OTHER DOCUMENTS** (Including Author, Title, Date, Pertinent Pages, Etc.)

TSP		Peterson et al., IBM Technical Disclosure Bulletin, "THERMALLY ENHANCED THREE-DIMENSIONAL FLEX INTERCONNECT OF MULTI-CHIP MODULES," Vol. 36, No. 12, December 1993, pg. 39

EXAMINER

*Shelby*

DATE CONSIDERED

08/20/04

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.





